L Number	Hits	Search Text	DB	Time Stamp
1	1	JP-63175751-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 09:13
6	1	1988JP-173721.ap,,ril.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 09:13
7	0	1988JP173721.ap,,ril.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 09:13
8	1	JP-62062092-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 09:14
9	741	(257/777).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 09:17
10	483	((257/777).CCLS.) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 09:18
13	205	(((257/777).CCLS.) and lead) and hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:55
14	6	("4945299" | "4956694" | "5193888" | "5257204" | "5266912" | "5448106").PN.	USPAT	2002/08/14 09:26
15	55	5193888.URPN.	USPAT	2002/08/14 09:27
16	4	("4945299" | "5138438" | "5138865" | "5440402").PN.	USPAT	2002/08/14 09:28
17	15	5801439.URPN.	USPAT	2002/08/14 09:28
18	1	JP-61120875-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:57
19	0	JP-43093284-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:12
20	25	coating with package with passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:15
21	531	coating with package with lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:15
22	51	coating with package with lead with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:23

33	2309	coating with lead with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 11:15
34	22	coating with lead with substrate with protect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 11:15
25	20	coating with package with substrate with protect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 11:26
26	3	coat with package with substrate with protect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 11:27
27	417	coat with substrate with protect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 11:27
28	33	(coat with substrate with protect, and coat with substrate with protect with semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 13:12
29	4779	passivate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 13:12
30	2338	passivate and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 13:12
31	763	passivate and semiconductor and (257/9).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 13:35
32	771	(257/+91).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 13:35
33	44	((257/691).CCLS.) and LED	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/14 13:35
-	0	jp08032106.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/13 11:12
-	0	jp08032106-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/13 11:12
-	2	JP-08032106-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/13 14:21

-	0	1994JP06185236.ap,prai.	THAI; ...; E.. ; ..; DERWENT; IBM_TDB	...11:13
-	0	1995JP06185236.ap,prai...	THAI; ...; E.. ; ..; DERWENT; IBM_TDB	...11:14
-	0	1995JP-6185236.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:14
-	0	1994JP-06185236.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:16
-	0	1994jp-185263.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:16
-	0	1994jp185263.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:16
-	0	1994jp0185263.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:16
-	138.	(257/99).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:18
-	193	(257/99).CCLS.) and lead and transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:52
-	3	("4102792" | "4307297" | "4780795" | "4451405" | "5289344" | "5659950" | "5907151" | "6066861").PN.	USPAT	2002/08/13 11:19
-	39	("3920405" | "4105777" | "4257061" "4257503" | "4394500" | "4729076" | "4911509" | "4995486" | "5032898" | "5060127" | "5113032" | "5136205" | "5173833" | "5181074" | "5235347" | "5291083" | "5363177" | "5384471" | "5434138" | "5468767" | "5472915" | "5610132" | "5556423" | "5680008" | "5703803" | "5777433" | "5733315" "5783792" | "5793044" | "5641177" "5869843" | "5885175" | "5913057" "5940683" | "5945117" | "5952684" "5958170" | "5959316" | "5966393").PN.	USPAT	2002/08/13 11:21

	31	("2961352" "3334444" "..." "3442949" "34554 5" "..." "3639979" "3752561" "..." "4133079" "4255752" "..." "4337182" "4362519" "4542222" "4641418" "4771525" "..." "4955808" "4951465" "..." "4996170" "5001222" "..." "5080980" "5047965" "..." "5089446" "5121442" "..." "5117779").PN.	USPAT	... 08/13 11:09
-	15	4777580.URPN.	USPAT	2002/08/13 11:23
-	4	("5110797" | "5551062" | "5646061" | "5644169").PN.	USPAT	2002/08/13 11:10
-	691	(@257 99).CCLS.) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:03
-	306	(@257 99).CCLS.) and (substrate with wiring printed board PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:03
-	162	(@257 99).CCLS.) and (substrate with wiring printed board PCB)) and LED	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:42
-	1	"5841177".PN.	USPAT	2002/08/13 12:18
-	7	("3191157" | "3772062" | "3776729" | "3931354" | "3935330" "3939488" "4010497").PN.	USPAT	2002/08/13 12:22
-	35	4255580.URPN.	USPAT	2002/08/13 12:23
-	8	("4103792" "4307297" | "4780795" | "4893695" | "5289344" | "5659950" | "5807151" | "6066861").PN.	USPAT	2002/08/13 12:24
-	0	("257").ccls. and lead with frame with LED and encapsul$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:43
-	41	@257 5.ccls. and lead with frame with LED and encapsul$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:48
-	0	LED with package with epoxy same plurality with outer with leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:49
-	1	LED with package with epoxy and plurality with outer with leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:50
-	1	LED with package with epoxy and plurality with external with leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:50
-	2	LED with epoxy and plurality with external with leads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:50

-	66	LED with epoxy and plurality with lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
-	27	("3711789" | "3764862" | "3832180" | "4054814" | "4123042" | "4153524" | "4157166" | "4371664" | "4435604" | "4542259" | "4661077" | "4814632" | "4855199" | "4862586" | "4890150" | "4893169" | "4935665" | "5012505" | "5062018" | "5174649" | "5218366" | "5241457" | "5276432" | "5294469" | "5401262" | "5436852").PN.	USPAT
-	27	5404142.URPN.	USPAT	2002/08/13 13:54
-	5	("4825625" | "5010463" | "5155669" | "5250049" | "5268828").PN.	USPAT	2002/08/13 13:55
-	4	5240043.URPN.	USPAT	2002/08/13 13:56
-	2	JP-04005652-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:25
-	1	1994JP-0045652.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24
-	1	1994JP-0246506.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:26
-	1	1994JP-0045652.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:26
-	2421	lead with frame with light	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:27
-	625	(lead with frame with light) and lead with (outer out external exterior)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:28
-	231	(lead with frame with light) and lead with (outer out external exterior)) and transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:45
-	8	("4263792" | "4307297" | "4780795" | "4801945" | "5289344" | "5659950" | "5867361" | "6066861").PN.	USPAT	2002/08/13 14:30
-	9	("3136164" | "3938173" | "4100362" | "4412215" | "4446375" | "4632432" | "4675241" | "4719358").PN.	USPAT	2002/08/13 14:31
-	35	4100362.URPN.	USPAT	2002/08/13 14:32
-	10	4642419.URPN.	USPAT	2002/08/13 14:33
-	7	5647034.URPN.	USPAT	2002/08/13 14:39
-	9	5554725.URPN.	USPAT	2002/08/13 14:40
-	7019	LED and toshiba.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:45

-	16	(LED and toshiba.as. and transparent with epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:47
-	2321	LED and slanted	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:4_
-	44	(LED and slanted) and (257/6).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:52
-	_	slanted with encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:02
-	176	slanted with package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:55
-	2998	(257/666).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:55
-	125	((257/666).CCLS.) and LED	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:02
-	1381	(257/99 .CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:03
-	374	((257/99).CCLS.) and transparent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:03
-	19?	(((257/99).CCLS.) and transparent) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:18
-	4	("4711129" | "5122860" | "5164815" | "5349732").PN.	USPAT	2002/08/13 15:06
-	1	5742098.URPN.	USPAT	2002/08/13 15:06
-	1	JP-59190757-$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:19
-	416	(257/667).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:21
-	13	((257/667).CCLS.) and LED	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:21

–	1644	(257/676).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
–	109	((257/676).CCLS.) and encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:14
–	3	("4750050" | "5594234" | "5665197").PN.	USPAT	2002/08/13 15:27
–	91	((257/676).CCLS.) and lead with perpendicular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:52
–	82	((257/676).CCLS.) and lead with perpendicular) not (((257/676).CCLS.) and encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:35
–	7	("4491086" | "5057805" | "5294897" | "5470492" | "5495125" | "5512781" | "5521429").PN.	USPAT	2002/08/13 15:38
–	7	5495125.URPN.	USPAT	2002/08/13 15:41
–	21	("4613102" | "4837184" | "4916413" | "5147815" | "5184207" | "5229640" | "5235496" | "5250841" | "5297008" | "5302421" | "5302521" | "5327104" | "5338971" | "5343072" | "5360992" | "5371408" | "5373188" | "5381037" | "5386068" | "5428319" | "5495125").PN.	USPAT	2002/08/13 15:42
–	8	("4947036" | "5157475" | "5442228" | "5900676" | "5973388" | "5977613" | "6021581" | "6107676").PN.	USPAT	2002/08/13 15:50
–	1332	(257/99).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:51
–	18	((257/99).CCLS.) and lead with perpendicular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:52
–	240	PCB with through with hole and LED	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:13
–	19	(PCB with through with hole and LED) and (257 $).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:12
–	149	PCB with through with hole and lead with frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:17
–	94239	board with through with hole same lead adj frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:19
–	220	board with through with hole same lead adj frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:34

- 343 wiring with board with lead with fixed

- 136 (wiring with board with lead with fixed,
       and board with hole